

AMENDMENT TO THE CLAIMS

1. (Currently amended) A glass-encapsulated light-emitting diode, comprising:

an LED bare chip;

a pair of electrodes, each connected to said LED bare chip on an opposite side thereof;

a pair of lead-in wires, each connected to one of said electrodes and thereby arranged for said LED bare chip to be interposed between said lead-in wires along an electrode direction; and

a pair of metallic members, each ~~connected to an other end of said lead~~ defining a hole through the center thereof, and

a glass encapsulation encapsulating ~~wherein~~ said LED bare chip, ~~including~~ said electrodes and at least a part of said lead-in wires, ~~are integrally encapsulated with glass to produce said glass-encapsulated light-emitting diode, and~~ wherein:

each said metallic members are ~~is~~ separately secured at both a respective end ~~ends~~ of said glass encapsulation and ~~glass-encapsulated light-emitting diode~~

each said lead-in wire extends from said glass encapsulation, into said hole in a respective one of said metallic members, but not beyond the end of said metallic member distal from said glass encapsulation.

2-4. (Canceled)

5. (Currently amended) The glass-encapsulated light-emitting diode according to claim 21, wherein glass for said ~~glass-~~

~~encapsulated light-emitting diode~~glass encapsulation is composed of soft glass.

6. (Currently amended) The glass-encapsulated light-emitting diode according to either claim 1 or claim 2, ~~wherein further comprising a solder plating~~ solder plating is applied on at least both outermost sides of said glass-encapsulated light-emitting diode in an extending direction of said pair of leads the ends of the metallic members distal from the glass encapsulation and on the ends of the lead-in wires distal from the glass encapsulation.

7-8. (Canceled)